

PSE Technology Corporation

SPECIFICATION FOR APPROVAL

CUSTOMER	
NOMINAL FREQUENCY	25.000000 MHz
PRODUCT TYPE	TYPE FW 2.0x1.6 SEAM SEALED CRYSTAI
PART NUMBER	FW2500025Z
CUSTOMER P/N	
ISSUE DATE	June 6, 2014
VERSION	С

APPROVED	PREPARED	QA	
Brenda	Nikbi Lu	Bedayeri	
	APPROVED BY CUSTOMER		

Please return one copy with approval to PSE-TW

PSE Technology Corporation

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- *Pb-free
- *RoHS Compliant
- *HF-Halogen Free
- *REACH Compliant

A Company of PERICOM Semiconductor Corporation

E0-R-4-014 Rev.E

VER.C 06-JUN-14

VERSION HISTORY

Version No.	Version Date	Customer Receipt Date	Supplier Receipt Date	Description	Notes
А	May. 28, 2014			Initial Release	
В	May. 29, 2014			Updated Calibration Load Capacitance to 20pF, ESR to 50 ohms max, C0 to 5pF max & Operating drive level to 10uW	
С	Jun. 6, 2014			Added Motional Capacitance 1.73fF & Motional Inductance 23.40mH	

VER.C 06-JUN-14

ELECTRICAL SPECIFICATIONS

Item	Symbol	Specifications	Units	Notes
Nominal Frequency	Fn	25.000000	MHz	
Mode of Oscillation	МО	AT Cut-Fundamental		
Calibration Load Capacitance	CL	20	pF	
Calibration Tolerance	FL	± 30	ppm	at 25°C±3°C
Operating Temperature Range	TR	-20 to +80	°C	
Frequency Stability(Frequency Deviation over the Operating Temperature Range)	F/T	± 30	ppm	Reference to the Frequency at 25°C
Operating Drive Level		10	μW	
Maximum Drive Level		200	μW	
Equivalent Series Resistance	ESR	50	Ω	Max.
Shunt Capacitance	C0	5	pF	Max.
Motional Capacitance	C1	1.73	fF	Тур.
Motional Inductance	L1	23.40	mH	Тур.
Aging at 25°C		± 3	ppm	Max, 1st year
Storage Temperature		-55 to +125	°C	
Insulation Resistance		500	ΜΩ	Min

^{**} This product doesn"t include harmful substance that stipulated by SONY SS-00259 Level 1 and S-AT2-001 Level 1 standard. RoHS Compliant (Pb - Free).

VER.C 06-JUN-14

RELIABILITY SPECIFICATIONS

MECHANICAL AND ENVIRONMENTAL RATINGS:

a)FINE LEAK TEST: JESD22-A109 (Condition 1A)

b)GROSS LEAK TEST: JESD22-A109 (Condition C)

c)MOISTURE RESISTANCE: JESD22-A113

d)SHOCK: JESD22-B104 (Condition B)

e)SOLDERABILITY: (RoHS version): J-STD-002

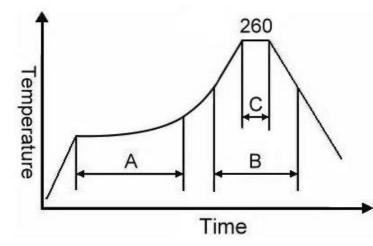
f)VIBRATION: JESD22-B103

g)SOLVENT RESISTANCE: JESD22-B107

h)RESISTANCE TO SOLDERING HEAT (RoHS version): J-STD-020D Table 5.2 Pb free devices (3 cycles max)

SUGGESTED IR REFLOW PROFILE

*As per IPC-JEDEC J-STD-020D



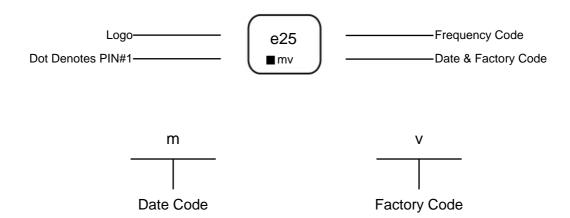
N	nt	-	
1.4	VI	c	

	Stage	Temperature	Time
Α	Preheat	150~200°C	60~120 Sec
В	Primary Heat	217°C	60~150 Sec
С	Peak	260°C	10 Sec

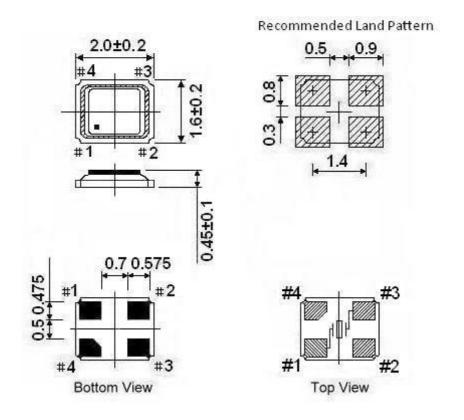
For soldering reflow profile and reliability test ratings go to: http://www.pericom.com/pdf/sre/reflow.pdf

VER.C 06-JUN-14

MARKING



MECHANICAL DRAWINGS (Scale: None. Dimensions are in mm.)



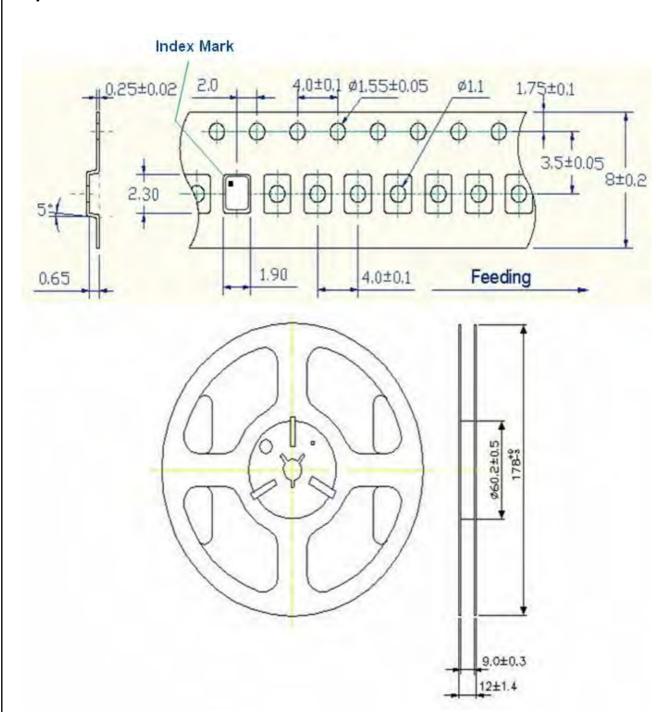
** Recommended - Pin 1 & 3: CRYSTAL Pin 2 & 4: GND

Notes:

- Package drawings are for reference only, and the appearances of objects may vary.
 Actual packages are based on the real product.
- 2. The marking dot denotes Pin#1.
- 3. The position and shape of the chamfer pin may vary and are based on the real product.

VER.C 06-JUN-14

Tape & Reel



- 1. 230mm minimum leafer which consist of carrier and/or tape followed by a minimum of 160mm of empty carrier tape sealed with cover tape.
- 2. 160mm minimum trailer of empty carrier tape sealed with cover tape.

VER.C 06-JUN-14

